1. LID O.D. TO BE .008 SMALLER THAN PACKAGE O.D. (.004 PER SIDE)

2. LID I.D. TO BE .008 SMALLER THAN PACKAGE I.D. (.004 PER SIDE)

   SEE ALSO DWGS 109-00083-002 & -003

3. LID STEP THICKNESS TO BE .005 MAX AFTER PLATING (RECOMMENDED LESS)

4. TYPICAL MATERIAL IS KOVAR

5. TYPICAL PLATING:
   A) NICKEL: ELECTROLESS/ELECTROLYTIC 50–150 MICROINCH.
   B) GOLD: 50 MICROINCH

6. LID DESIGN SHOULD BE SUCH THAT THE LID IS NEVER LARGER THAN THE SEAL RING.
1. LID O.D. TO BE .008 SMALLER THAN BRAZE RING O.D. (.004 PER SIDE)
2. LID I.D. TO BE .008 SMALLER THAN BRAZE RING I.D. (.004 PER SIDE)
   SEE ALSO DWGS 109-00083-002 & -003

3. LID STEP THICKNESS TO BE .005 MAX AFTER PLATING (RECOMMENDED LESS)

4. LID DESIGN SHOULD BE SUCH THAT THE LID IS NEVER LARGER THAN THE SEAL RING.
SEE DETAIL A

SEAL RING

NOT ENOUGH CLEARANCE BETWEEN LID STEP AND SEAL RING I.D.

DETAIL A

0.004" TYP. FROM LID O.D. TO SEAL RING O.D.

0.004" TYP

SUFFICIENT CLEARANCE BETWEEN LID STEP AND SEAL RING I.D.

THESE DIMENSIONS SHOULD BE EQUAL TO PREVENT THE LID FROM OVERHANGING THE SEAL RING
SEE DETAIL A

90° CORNERS ON LID AND PACKAGE—UNDESIRABLE

DETAIL A

DETAIL B

RAD. .020" MIN ON PACKAGE

DETAIL B

SHOULD HAVE CORNER RADII AS SHOWN IN DETAIL B